

# Conference Programme Day 1, Thursday February 1

08:00-08:30	Conference Registration and Table Top & Poster Exhibition build up	Table Top & Poster Display Area
08:30-08:40	Welcome by the EIPC Chairman	Alun Morgan, EIPC, UK
08:40-08:45	Welcome by Alstom	Christian Roth, Alstom, FR
<b>Keynote Session: Business, Technology &amp; New Developments</b>		<b>Moderator: Alun Morgan, EIPC, UK</b>
08:45-09:30	Business Outlook: Global Electronics Industry	Walt Custer, Custer Consulting, USA
09:30-10:00	From Semiconductor Die to PCB: Changing Landscapes and Future Requirements	Thibault Buisson, Yole Developpement, FR
10:00-10:30	Present and future solutions for the Electronics Industry in Europe	Dr. Martin Schrems, AT & S Austria Technologie & Systemtechnik Aktiengesellschaft, AT
10:30-10:45	Panel discussion	
10:45-11:15	Coffee break	
<b>Session 1: Trends and capabilities in PCB fabrication</b>		<b>Moderator: Martyn Gaudion, Polar Instruments, UK</b>
11:15-11:35	Future automotive requirements	Dr. Christian Klein, Robert Bosch GmbH, DE
11:35-11:55	s. mask: solder mask 4.0	Dr. Lothar Weitzel, Würth Elektronik GmbH & Co. KG, DE
11:55-12:15	Miniaturized Hermetic Modules for Sensor Integration	Dr. Marc Hauer, Dyconex AG, CH
12:15-12:35	ULDK for high speed loss designs	Tamara den Daas-Wijnen, Ventec International Group, NL
<b>12:35-13:45</b>	<b>Networking Lunch</b>	<b>Alstom Restaurant</b>
13:45-14:15	PCB material toolbox for today's 3 and 4G networks and future high speed needs in 5G in the most cost effective and environmental way	Stig Källman, Ericsson, SE
14:15-14:35	5G design feature driven PCB Technology & Process and presented	Erkko Helminen, TTM Technologies, HK
14:35-14:55	Panel discussion	
<b>Session 2: Reliability</b>		<b>Moderator: Emma Hudson, UL, UK</b>
14:55-15:15	Panel and Roll to Roll AOI and AVI already in production for PCB and components. EDI in development	Gregory Stoeckli, First EIE, CH
15:15-15:35	Defects through Ionic Contamination. Process and finish product control using IEC 61189-5	Graham Naisbitt, Gen3 Systems Ltd, UK
15:35-16:05	Reliability of multi-level HDI structures and Reliability of Back-drilling	Bill Birch, PWB Interconnect Solutions, CA
16:05-16:25	Electronic requirements for global Railway / Trains markets	José Taborda, Alstom, FR
16:25-16:40	Panel discussion	
<b>16:45-18:45</b>	<b>Tour Alstom</b>	
<b>18:45-21:45</b>	<b>Network Dinner Brasserie Georges Lyon Centre</b>	
<b>22:00</b>	<b>Return and arrival at Headquarter Hotel Ibis</b>	

*The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters. Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.*



## Conference Programme Day 2, Friday February 2

<b>Session 3: Process Improvements</b>		<b>Moderator: John Fix, Taiyo, US</b>
09:00-09:20	Future PCB fabrication and material requirements for the global industry segments	Grace O'Malley, iNEMI, UK
09:20-09:40	Using Raw Data to develop an Intelligent Manufacturing Solution for the problem of registration control within the PCB "Smart Factory"	Andrew Kelley, Xact PCB, UK
09:40-10:00	How AOI can enhance the ability to control the pcb manufacturing process	TBA, Orbotech, BE
10:00-10:20	Redefining your solder mask needs with ink jetting	Don Monn, Taiyo, US
10:20-10:30	Panel discussion	
<b>10:30-11:00</b>	<b>30 minutes Coffee break</b>	<b>Table Top &amp; Poster Display Area</b>
<b>Session 4: European needs for New Technology, Product Safety and Training</b>		<b>Moderator: Dr. Michele Stampanoni, Cikor, CH</b>
11:00-11:20	Safety and reliability Standarization IEC standards and the role of UL in the global market	Emma Hudson, UL, UK
11:20-11:40	Printed Electronics for Flexible and Conformal Applications	Neil Chilton, Printed Electronics, UK
11:40-12:00	DuPont Photovoltaic and Advanced Materials for Printed Electronics	Hortense Gaya, CCI Eurolam, FR
12:00-12:30	FED Training Programme "Certified Electronics Designer"	Christoph Bornhorn, Fachverband Elektronik-Design, DE
12:30-12:50	3D printer Dragon Fly for PCB prototyping and electronics manufacturing	Robert Even, Nano Dimension, IL
12:50-13:05	Panel Discussion	
<b>13:05-13:10</b>	<b>Chairman closing remarks - End of conference day 2</b>	
<b>13:10-14:15</b>	<b>Networking Lunch</b>	<b>Alstom Restaurant</b>

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